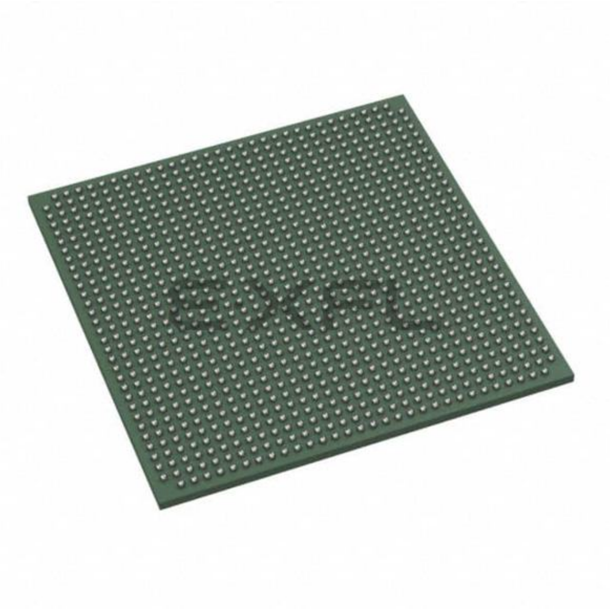
Lattice Semiconductor Corporation - LFSCM3GA25EP1-5FFN1020I Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

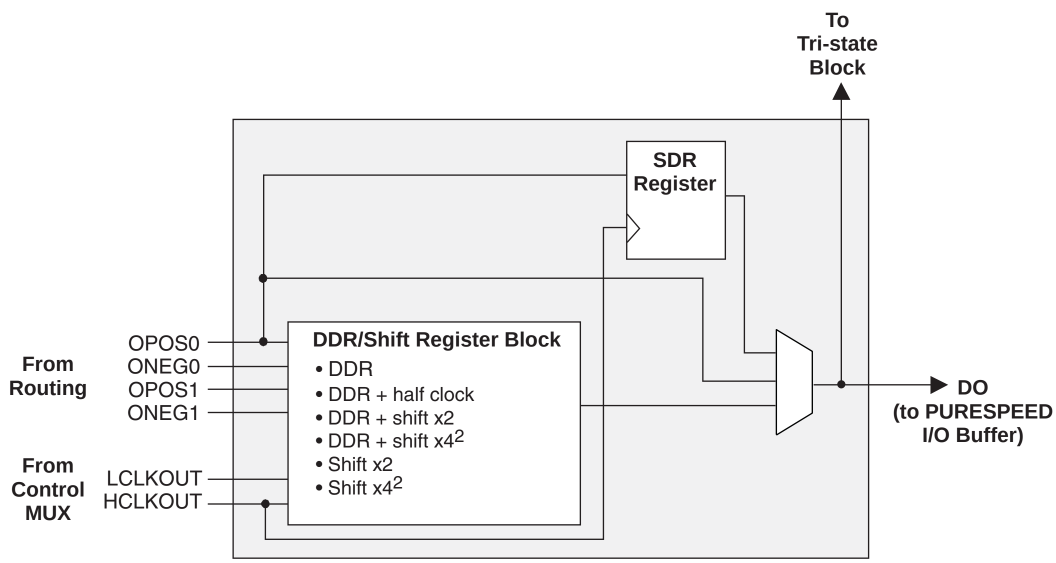
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

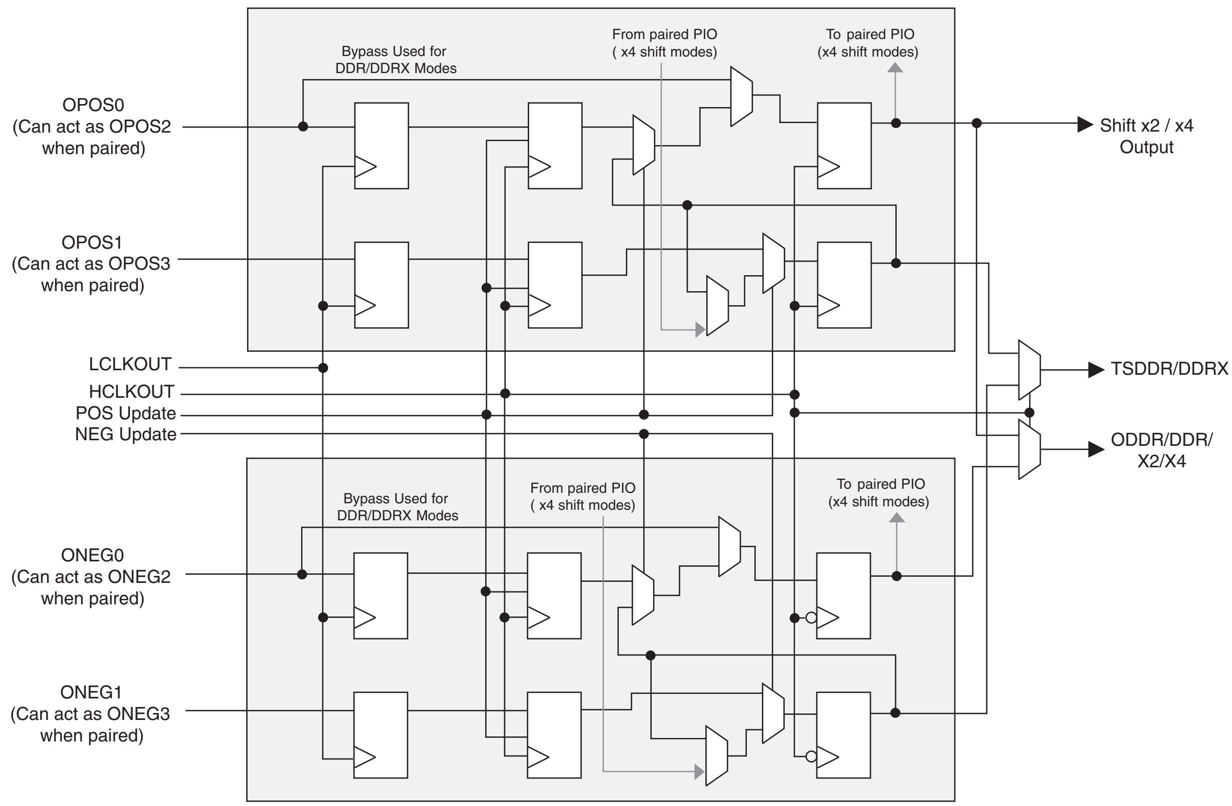
Details	
Product Status	Obsolete
Number of LABs/CLBs	6250
Number of Logic Elements/Cells	25000
Total RAM Bits	1966080
Number of I/O	476
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFCBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga25ep1-5ffn1020i

Figure 2-22. Output Register Block[1]



Notes:
1. CE, Update, Set and Reset not shown for clarity.
2. By four shift modes utilizes DDR/Shift register block from paired PIO.
3. DDR/Shift register block shared with tristate block.

Figure 2-23. Output/Tristate DDR/Shift Register Block



3. **Bottom Side (Banks 4 and 5)**
   These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but true HLVDS and RSDS differential drivers are not available. Adaptive input logic is available on PIOs A or C.

Table 2-8 lists the standards supported by each side.

Table 2-8. I/O Standards Supported by Different Banks

Description	Top Side Banks 1	Right Side Banks 2-3	Bottom Side Banks 4-5	Left Side Banks 6-7
I/O Buffer Type	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver
Output Standards Supported	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]
Input Standards Supported	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Clock Inputs	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Differential Output Support via Emulation	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL
AIL Support	No	Yes	Yes	Yes

1. Input only.
2. Input only. Outputs supported by bussing multiple outputs together.

Supported Standards

The LatticeSC PURESPEED I/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 12, 15, 18, 25 and 33 standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, termination resistance, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL, HSTL, GTL (input only), GTL+ (input only), PCI33, PCIX33, PCIX15, AGP-1X33 and AGP-2X33. Differential standards supported include LVDS, RSDS, BLVDS, MLVDS, LVPECL, differential SSTL and differential HSTL. Tables 12 and 13 show the I/O standards (together with their supply and reference voltages) supported by the LatticeSC devices. The tables also provide the available internal termination schemes. For further information on utilizing the PURESPEED I/O buffer to support a variety of standards please see details of additional technical documentation at the end of this data sheet.

Table 2-9. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)	On-chip Termination
Single Ended Interfaces			
LVTTL33[3]	—	3.3	None
LVCMOS 33, 25, 18, 15, 12[3]	—	3.3/2.5/1.8/1.5/1.2	None
PCI33, PCIX33, AGP1X33[3]	—	3.3	None
PCIX15	0.75	1.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
AGP2X33	1.32	—	None
HSTL18_I, II	0.9	1.8[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL18_III, IV	1.08	1.8[2]	None / V_{CCIO}: 50
HSTL15_I, II	0.75	1.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL15_III, IV	0.9	1.5[2]	None / V_{CCIO}: 50
SSTL33_I, II	1.5	3.3	None
SSTL25_I, II	1.25	2.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL18_I, II	0.9	1.8[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
GTL+, GTL	1.0 / 0.8	1.5 / 1.2[2]	None / V_{CCIO}: 50
Differential Interfaces			
SSTL18D_I, II	—	1.8[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL25D_I, II	—	2.5[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL33D_I, II	—	3.3	None
HSTL15D_I, II	—	1.5[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL18D_I, II	—	1.8[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
LVDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240
Mini-LVDS	—	—	None / Diff: 120, 150 / Diff to V_{CMT}: 120, 150
BLVDS25	—	—	None
MLVDS25	—	—	None
RSDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240
LVPECL33	—	≤2.5	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.
2. V_{CCIO} needed for on-chip termination to $V_{CCIO}/2$ or V_{CCIO} only. V_{CCIO} is not specified for off-chip termination or V_{TT} termination.
3. All ratioed input buffers and dedicated pin input buffers include hysteresis with a typical value of 50mV.

this allows for easy integration with the rest of the system. These capabilities make the LatticeSC ideal for many multiple power supply and hot-swap applications. The maximum current during hot socketing is 4mA. See Hot Socketing Specifications in Chapter 3 of this data sheet.

Power-Up Requirements

To prevent high power supply and input pin currents, each VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies must have a monotonic ramp up time of 75 ms or less to reach its minimum operating voltage. Apart from VCC and VCC12, which have an additional requirement, and VCCIO and VCCAUX, which also have an additional requirement, the VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies can ramp up in any order, with no restriction on the time between them. However, the ramp time for each must be 75 ms or less. Configuration of the device will not proceed until the last power supply has reached its minimum operating voltage.

Additional Requirement for VCC and VCC12:

VCC12 must always be higher than VCC. This condition must be maintained at ALL times, including during power-up and power-down. Note that for 1.2V only operation, it is advisable to source both of these supplies from the same power supply.

Additional Requirement for VCCIO and VCCAUX:

If any VCCIOs are 1.2/1.5/1.8V, then VCCAUX MUST be applied before them. If any VCCIO is 1.2/1.5/1.8V and is powered up before VCCAUX, then when VCCAUX is powered up, it may drag VCCIO up with it as it crosses through the VCCIO value. (Note: If the VCCIO supply is capable of sinking current, as well as the more usual sourcing capability, this behavior is eliminated. However, the amount of current that the supply needs to sink is unknown and is likely to be in the hundreds of milliamps range).

Power-Down Requirements

To prevent high power supply and input pin currents, power must be removed monotonically from either VCC or VCCAUX (and must reach the power-down trip point of 0.5V for VCC, 0.95V for VCCAUX) before power is removed monotonically from VCC12, any of the VCCIOs, or VCCJ. Note that VCC12 can be removed at the same time as VCC, but it cannot be removed earlier. In many applications, VCC and VCC12 will be sourced from the same power supply and so will be removed together. For systems where disturbance of the user pins is a don't care condition, the power supplies can be removed in any order as long as they power down monotonically within 200ms of each other.

Additionally, if any banks have VCCIO=3.3V nominal (potentially banks 1, 4, 5) then VCCIO for those banks must not be lower than VCCAUX during power-down. The normal variation in ramp-up times of power supplies and voltage regulators is not a concern here.

Note: The SERDES power supplies are NOT included in these requirements and have no specific sequencing requirements. However, when using the SERDES with VDDIB or VDDOB that is greater than 1.2V (1.5V nominal for example), the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in the ramp-up times of power supplies and voltage regulators is not a concern here.

SERDES Power Supply Sequencing Requirements

When using the SERDES with 1.5V VDDIB or VDDOB supplies, the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and the 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in ramp-up times of power supples and voltage regulators is not a concern.

Additional Requirement for SERDES Power Supply

All VCC12 pins need to be connected on all devices independent of functionality used on the device. This analog supply is used by both the RX and TX portions of the SERDES and is used to control the core SERDES logic regardless of the SERDES being used in the design. VDDIB and VDDOB are used as supplies for the terminations on the CML input and output buffers. If a particular channel is not used, these can be UNCONNECTED (floating).

Absolute Maximum Ratings

Supply Voltage V_{CC}, V_{CC12}, V_{DDIB}, V_{DDOB} . . . . -0.5 to 1.6V

Supply Voltage V_{CCAUX}, V_{DDAX25}, V_{TT} . . . . -0.5 to 2.75V

Supply Voltage V_{CCJ} . . . . -0.5 to 3.6V

Supply Voltage V_{CCIO} (Banks 1, 4, 5) . . . . -0.5 to 3.6V

Supply Voltage V_{CCIO} (Banks 2, 3, 6, 7) . . . . -0.5 to 2.75V

Input or I/O Tristate Voltage Applied (Banks 1, 4, 5) . . . . -0.5 to 3.6V

Input or I/O Tristate Voltage Applied (Banks 2, 3, 6, 7) . . . . -0.5 to 2.75V

Storage Temperature (Ambient). . . . . -65 to 150°C

Junction Temperature Under Bias (Tj) . . . . +125°C

Notes:
1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Undershoot and overshoot of -2V to (VIHMAX +2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}[5]	Core Supply Voltage (Nominal 1.2V Operation)	0.95	1.26	V
V_{CCAUX}[6]	Programmable I/O Auxiliary Supply Voltage	2.375	2.625	V
V_{CCIO}[1, 2, 5, 6]	Programmable I/O Driver Supply Voltage (Banks 1, 4, 5)	1.14	3.45	V
V_{CCIO}[1, 2, 5, 6]	Programmable I/O Driver Supply Voltage (Banks 2, 3, 6, 7)	1.14	2.625	V
V_{CC12}[4, 5]	Internal 1.2V Power Supply Voltage for Configuration Logic and FPGA PLL, SERDES PLL Power Supply Voltage and SERDES Analog Supply Voltage	1.14	1.26	V
V_{DDIB}	SERDES Input Buffer Supply Voltage	1.14	1.575	V
V_{DDOB}	SERDES Output Buffer Supply Voltage	1.14	1.575	V
V_{DDAX25}	SERDES Termination Auxiliary Supply Voltage	2.375	2.625	V
V_{CCJ}[1, 5]	Supply Voltage for IEEE 1149.1 Test Access Port	1.71	3.45	V
V_{TT}[2, 3]	Programmable I/O Termination Power Supply	0.5	V_{CCAUX} - 0.5	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	+85	C
t_{JIND}	Junction Temperature, Industrial Operation	-40	105	C

1. If V_{CCIO} or V_{CCJ} is set to 2.5V, they must be connected to the same power supply as V_{CCAUX}.
2. See recommended voltages by I/O standard in subsequent table.
3. When V_{TT} termination is not required, or used to provide the common mode termination voltage (V_{CMT}), these pins can be left unconnected on the device.
4. V_{CC12} cannot be lower than V_{CC} at any time. For 1.2V operation, it is recommended that the V_{CC} and V_{CC12} supplies be tied together with proper noise decoupling between the digital VCC and analog VCC12 supplies.
5. V_{CC}, V_{CCIO} (all banks), V_{CC12} and V_{CCJ} must reach their minimum values before configuration will proceed.
6. If V_{CCIO} for a bank is nominally 1.2V/1.5V/1.8V, then V_{CCAUX} must always be higher than V_{CCIO} during power up.

Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

MLVDS

The LatticeSC devices support the MLVDS standard. This industry standard is emulated using controlled impedance complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. MLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-1 is one possible solution for bi-directional multi-point differential signals.

Figure 3-1. MLVDS Multi-Point Output Example

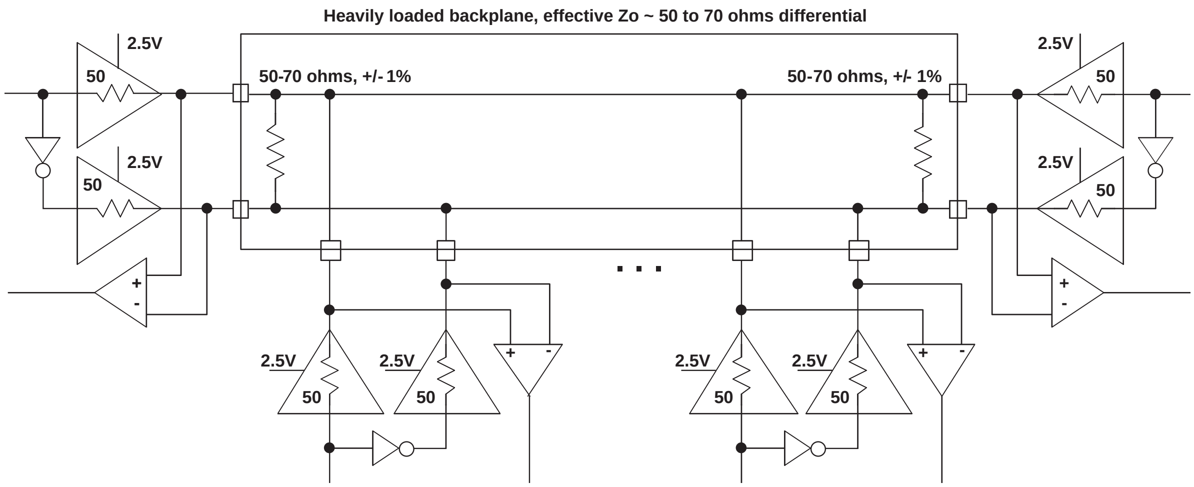


Table 3-1. MLVDS DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal Zo = 50	Nominal Zo = 70	Units
Z_{OUT}	Output impedance	50	50	ohm
R_{TLEFT}	Left end termination	50	70	ohm
R_{TRIGHT}	Right end termination	50	70	ohm
V_{OH}	Output high voltage	1.50	1.575	V
V_{OL}	Output low voltage	1.00	0.925	V
V_{OD}	Output differential voltage	0.50	0.65	V
V_{CM}	Output common mode voltage	1.25	1.25	V
I_{DC}	DC output current	20.0	18.5	mA

1. For input buffer, see LVDS table.

LVPECL

The LatticeSC devices support differential LVPECL standard. This standard is emulated using controlled impedance complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

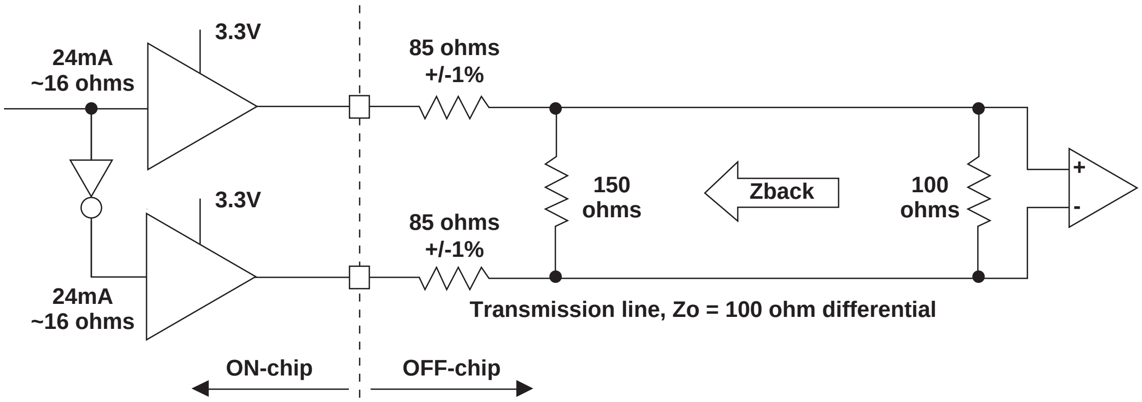


Table 3-3. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal	Units
Z_{OUT}	Output impedance	16	ohm
R_S	Driver series resistor	85	ohm
R_P	Driver parallel resistor	150	ohm
R_T	Receiver termination	100	ohm
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	86	ohm
I_{DC}	DC output current	12.6	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS, MLVDS and other differential interfaces please see details of additional technical documentation at the end of this data sheet.

On-die Differential Common Mode Termination

Symbol	Description	Min.	Typ.	Max.	Units
C_{CMT}	Capacitance V_{CMT} to GND	—	40	—	pF

Input Delay Block/AIL Timing

Parameter	Description	Min.	Typ.	Max.	Units
t_{FDEL}	Fine delay time	35	45	80	ps
t_{CDEL}	Coarse delay time	1120	1440	2560	ps
jt_{AIL}	AIL jitter tolerance	1- ((N[1] * t_{FDEL}) / (Clock Period))			UI

1. N = number of fine delays used in a particular AIL setting

GSR Timing

Parameter	Description	VCC	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
$t_{SYNC\_GSR\_MAX}$	Maximum operating frequency for synchronous GSR	1.14V	—	438	—	417	—	398	MHz
		0.95V	—	378	—	355	—	337	MHz
$t_{ASYNC\_GSR\_MPW}$	Minimum pulse width of asynchronous input	—	—	—	—	—	3.3	—	ns

Note: Synchronous GSR goes out of reset in two cycles from the clock edge where the setup time of the FF was met.

Internal System Bus Timing

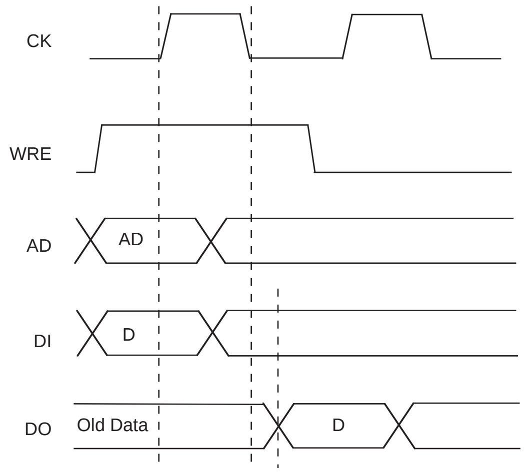
Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{HCLK}	Maximum operating frequency for internal system bus HCLK.	—	200	—	200	—	200	MHz

Note: There is no minimum frequency. If HCLK is sourced from the embedded oscillator, the minimum frequency limitation of the oscillator/divider is about 0.3 MHz. Refer to the osciallator data for missing configuration modes.

Timing Diagrams

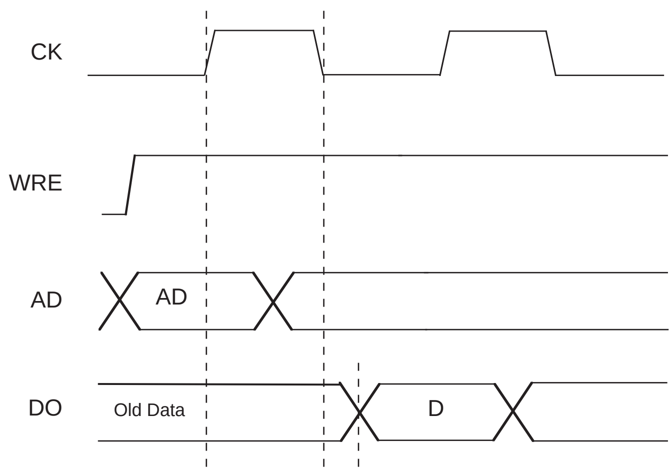
PFU Timing Diagrams

Figure 3-4. Slice Single/Dual Port Write Cycle Timing



Notes:
- Rising Edge for latching WREN, WAD and DATAIN.
- WREN must continue past falling edge clock.
- Data output occurs on negative edge.

Figure 3-5. Slice Single/Dual Port Read Cycle Timing



LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2]

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
E4	A_VDDAX25_L	-	
B1	A_REFCLKP_L	-	
C1	A_REFCLKN_L	-	
D2	RESP_ULC	-	
F5	RESETN	1	
D1	DONE	1	
E1	INITN	1	
E2	M0	1	
E3	M1	1	
E5	M2	1	
E6	M3	1	
F2	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
F1	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
F3	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
G1	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
G4	PL18D	7	VREF2_7
H3	PL22A	7	
H2	PL22B	7	
H5	PL22C	7	VREF1_7
G5	PL22D	7	DIFFR_7
H1	PL23A	7	PCLKT7_1
J1	PL23B	7	PCLKC7_1
J2	PL24A	7	PCLKT7_0
J3	PL24B	7	PCLKC7_0
H4	PL24C	7	PCLKT7_2
H6	PL24D	7	PCLKC7_2
J4	PL26A	6	PCLKT6_0
K5	PL26B	6	PCLKC6_0
J5	PL26C	6	PCLKT6_1
J6	PL26D	6	PCLKC6_1
K1	PL28A	6	
L1	PL28B	6	
L4	PL28C	6	PCLKT6_2
K4	PL28D	6	PCLKC6_2
L2	PL31C	6	VREF1_6
L3	PL35A	6	
M3	PL35B	6	
M2	PL35D	6	DIFFR_6
M1	PL37A	6	
N1	PL37B	6	
P2	PL41D	6	VREF2_6
M5	PL43A	6	

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2] (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
N12	PB39C	4	
T15	PB40A	4	PCLKT4_3
R16	PB40B	4	PCLKC4_3
L12	PB43A	4	
M12	PB43B	4	
P16	PB44A	4	
N16	PB44B	4	
R14	PB47C	4	VREF1_4
P15	PB48A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
M13	PB48B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
N13	PB49A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
P14	PB49B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
M16	PR45B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
L16	PR45A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
M14	PR43B	3	
M15	PR43A	3	
K16	PR41D	3	VREF2_3
J16	PR37B	3	
H16	PR37A	3	
L13	PR35D	3	DIFFR_3
L14	PR35B	3	
L15	PR35A	3	
K12	PR31C	3	VREF1_3
J13	PR28D	3	PCLKC3_2
K13	PR28C	3	PCLKT3_2
H15	PR28B	3	
F16	PR28A	3	
J11	PR26D	3	PCLKC3_1
J12	PR26C	3	PCLKT3_1
J15	PR26B	3	PCLKC3_0
J14	PR26A	3	PCLKT3_0
E16	PR24D	2	PCLKC2_2
D16	PR24C	2	PCLKT2_2
H11	PR24B	2	PCLKC2_0
H12	PR24A	2	PCLKT2_0
H13	PR23B	2	PCLKC2_1
H14	PR23A	2	PCLKT2_1
G12	PR22D	2	DIFFR_2
G13	PR22C	2	VREF1_2
F8	PR22B	2	
F9	PR22A	2	
G16	PR18D	2	VREF2_2
F15	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2] (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
F14	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
E15	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
E14	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
D9	VCCJ	-	
C16	TDO	-	TDO
B15	TMS	-	
B16	TCK	-	
E13	TDI	-	
C14	PROGRAMN	1	
C15	CCLK	1	
A15	PT43D	1	HDC/SI
A14	PT43C	1	LDCN/SCS
B14	PT41A	1	CS1
E12	PT39B	1	CS0N
D13	PT39A	1	RDN
D12	PT37D	1	WRN
E10	PT37C	1	D7
C11	PT37B	1	D6
D10	PT37A	1	D5
A13	PT36D	1	D4
B12	PT36C	1	D3
A12	PT35B	1	D2
C12	PT35A	1	D1
A11	PT33B	1	D0
B11	PT33A	1	QOUT/CEON
E9	PT32D	1	VREF2_1
E8	PT32B	1	DOUT
D8	PT28C	1	BUSYN/RCLK/SCK
A10	PT27B	1	PCLKC1_0
C10	PT27A	1	PCLKT1_0
E7	PT21C	1	VREF1_1
C9	A_VDDIB3_L	-	
A9	A_HDINP3_L	-	PCS 360 CH 3 IN P
B9	A_HDINN3_L	-	PCS 360 CH 3 IN N
A8	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
B8	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
C8	A_VDDOB3_L	-	
B7	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
C7	A_VDDOB2_L	-	
A7	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
B6	A_HDINN2_L	-	PCS 360 CH 2 IN N
A6	A_HDINP2_L	-	PCS 360 CH 2 IN P
C6	A_VDDIB2_L	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

	LFSC/M15			LFSC/M25		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AF4	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AE5	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AG3	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AH2	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AD6	PB4C	5		PB4C	5	
AJ2	PB5A	5		PB5A	5	
AK2	PB5B	5		PB5B	5	
AD7	PB5C	5		PB5C	5	
AD8	PB5D	5	VREF1_5	PB5D	5	VREF1_5
AH3	PB7A	5		PB11A	5	
AJ3	PB7B	5		PB11B	5	
AF9	PB7C	5		PB11C	5	
AE10	PB7D	5		PB11D	5	
AK3	PB8A	5		PB12A	5	
AJ4	PB8B	5		PB12B	5	
AE11	PB9A	5		PB13A	5	
AF10	PB9B	5		PB13B	5	
AK4	PB11A	5		PB16A	5	
AK5	PB11B	5		PB16B	5	
AH10	PB12A	5	PCLKT5_3	PB20A	5	PCLKT5_3
AH11	PB12B	5	PCLKC5_3	PB20B	5	PCLKC5_3
AF13	PB12C	5	PCLKT5_4	PB20C	5	PCLKT5_4
AE14	PB12D	5	PCLKC5_4	PB20D	5	PCLKC5_4
AK6	PB13A	5	PCLKT5_5	PB21A	5	PCLKT5_5
AK7	PB13B	5	PCLKC5_5	PB21B	5	PCLKC5_5
AF14	PB13C	5		PB21C	5	
AJ11	PB15A	5	PCLKT5_0	PB23A	5	PCLKT5_0
AJ12	PB15B	5	PCLKC5_0	PB23B	5	PCLKC5_0
AH13	PB15D	5	VREF2_5	PB23D	5	VREF2_5
AK8	PB16A	5	PCLKT5_1	PB24A	5	PCLKT5_1
AK9	PB16B	5	PCLKC5_1	PB24B	5	PCLKC5_1
AH14	PB17A	5	PCLKT5_2	PB25A	5	PCLKT5_2
AG14	PB17B	5	PCLKC5_2	PB25B	5	PCLKC5_2
AK10	PB19A	5		PB28A	5	
AK11	PB19B	5		PB28B	5	
AH15	PB20A	5		PB29A	5	
AG15	PB20B	5		PB29B	5	
AH12	PB21A	5		PB31A	5	
AJ13	PB21B	5		PB31B	5	
AD15	PB21C	5		PB31C	5	
AE15	PB21D	5		PB31D	5	
AK12	PB23A	5		PB32A	5	
AK13	PB23B	5		PB32B	5	
AJ14	PB24A	5		PB33A	5	
AJ15	PB24B	5		PB33B	5	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

	LFSC/M15			LFSC/M25		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
A29	RESP_URC	-		RESP_URC	-	
D26	VCC12	-		VCC12	-	
C30	A_REFCLKN_R	-		A_REFCLKN_R	-	
B30	A_REFCLKP_R	-		A_REFCLKP_R	-	
F24	A_VDDAX25_R	-		A_VDDAX25_R	-	
D25	VCC12	-		VCC12	-	
C28	A_VDDIB0_R	-		A_VDDIB0_R	-	
B28	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
B27	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
E25	VCC12	-		VCC12	-	
A28	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
C27	A_VDDOB0_R	-		A_VDDOB0_R	-	
A27	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
C26	A_VDDOB1_R	-		A_VDDOB1_R	-	
A26	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
D24	VCC12	-		VCC12	-	
A25	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
B26	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
B25	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
E24	VCC12	-		VCC12	-	
C25	A_VDDIB1_R	-		A_VDDIB1_R	-	
D23	VCC12	-		VCC12	-	
C24	A_VDDIB2_R	-		A_VDDIB2_R	-	
B24	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
B23	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
E23	VCC12	-		VCC12	-	
A24	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
C23	A_VDDOB2_R	-		A_VDDOB2_R	-	
A23	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
C22	A_VDDOB3_R	-		A_VDDOB3_R	-	
A22	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
D22	VCC12	-		VCC12	-	
A21	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
B22	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
B21	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
E22	VCC12	-		VCC12	-	
C21	A_VDDIB3_R	-		A_VDDIB3_R	-	
G22	PT43D	1	HDC/SI	PT49D	1	HDC/SI
F22	PT43C	1	LDCN/SCS	PT49C	1	LDCN/SCS
B20	PT41B	1	D8/MPI_DATA8	PT49B	1	D8/MPI_DATA8
B19	PT41A	1	CS1/MPI_CS1	PT49A	1	CS1/MPI_CS1
A20	PT40D	1	D9/MPI_DATA9	PT47D	1	D9/MPI_DATA9
A19	PT40C	1	D10/MPI_DATA10	PT47C	1	D10/MPI_DATA10
D19	PT39B	1	CS0N/MPI_CS0N	PT47B	1	CS0N/MPI_CS0N
D18	PT39A	1	RDN/MPI_STRB_N	PT47A	1	RDN/MPI_STRB_N

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

	LFSC/M40			LFSC/M80		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH27	PB5C	5		PB5C	5	
AH26	PB5D	5	VREF1_5	PB5D	5	VREF1_5
AN32	PB7A	5		PB7A	5	
AP32	PB7B	5		PB7B	5	
AF25	PB7C	5		PB7C	5	
AE25	PB7D	5		PB7D	5	
AN31	PB8A	5		PB9A	5	
AN30	PB8B	5		PB9B	5	
AK29	PB8C	5		PB9C	5	
AK28	PB8D	5		PB9D	5	
AP31	PB9A	5		PB11A	5	
AP30	PB9B	5		PB11B	5	
AD24	PB9C	5		PB11C	5	
AE24	PB9D	5		PB11D	5	
AM29	PB11A	5		PB13A	5	
AM28	PB11B	5		PB13B	5	
AJ27	PB11C	5		PB13C	5	
AJ26	PB11D	5		PB13D	5	
AP29	PB13A	5		PB15A	5	
AP28	PB13B	5		PB15B	5	
AK27	PB13C	5		PB15C	5	
AK26	PB13D	5		PB15D	5	
AN29	PB15A	5		PB17A	5	
AN28	PB15B	5		PB17B	5	
AG25	PB15C	5		PB17C	5	
AG24	PB15D	5		PB17D	5	
AL26	PB17A	5		PB19A	5	
AL25	PB17B	5		PB19B	5	
AG23	PB17C	5		PB19C	5	
AG22	PB17D	5		PB19D	5	
AN27	PB19A	5		PB21A	5	
AN26	PB19B	5		PB21B	5	
AF24	PB19C	5		PB21C	5	
AF23	PB19D	5		PB21D	5	
AP27	PB22A	5		PB24A	5	
AP26	PB22B	5		PB24B	5	
AK25	PB22C	5		PB24C	5	
AK24	PB22D	5		PB24D	5	
AN25	PB25A	5		PB27A	5	
AN24	PB25B	5		PB27B	5	
AE22	PB25C	5		PB27C	5	
AE21	PB25D	5		PB27D	5	
AM26	PB26A	5		PB29A	5	
AM25	PB26B	5		PB29B	5	
AF22	PB26C	5		PB29C	5	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

	LFSC/M40			LFSC/M80		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
H21	PT38D	1	D28/PCLKC1_6/MPI_DATA28	PT57D	1	D28/PCLKC1_6/MPI_DATA28
J21	PT38C	1	D29/PCLKT1_6/MPI_DATA29	PT57C	1	D29/PCLKT1_6/MPI_DATA29
A19	PT38B	1	A9/MPI_ADDR23	PT57B	1	A9/MPI_ADDR23
B19	PT38A	1	A10/MPI_ADDR24	PT57A	1	A10/MPI_ADDR24
H22	PT37D	1	D30/PCLKC1_7/MPI_DATA30	PT56D	1	D30/PCLKC1_7/MPI_DATA30
J22	PT37C	1	D31/PCLKT1_7/MPI_DATA31	PT56C	1	D31/PCLKT1_7/MPI_DATA31
F20	PT37B	1	A11/MPI_ADDR25	PT56B	1	A11/MPI_ADDR25
G20	PT37A	1	A12/MPI_ADDR26	PT56A	1	A12/MPI_ADDR26
K21	PT35D	1	D11/MPI_DATA11	PT55D	1	D11/MPI_DATA11
K22	PT35C	1	D12/MPI_DATA12	PT55C	1	D12/MPI_DATA12
A20	PT35B	1	A13/MPI_ADDR27	PT55B	1	A13/MPI_ADDR27
B20	PT35A	1	A14/MPI_ADDR28	PT55A	1	A14/MPI_ADDR28
L21	PT33D	1	A16/MPI_ADDR30	PT53D	1	A16/MPI_ADDR30
L20	PT33C	1	D13/MPI_DATA13	PT53C	1	D13/MPI_DATA13
D20	PT33B	1	A15/MPI_ADDR29	PT53B	1	A15/MPI_ADDR29
E20	PT33A	1	A17/MPI_ADDR31	PT53A	1	A17/MPI_ADDR31
L19	PT30D	1	A19/MPI_TSIZ1	PT52D	1	A19/MPI_TSIZ1
K19	PT30C	1	A20/MPI_BDIP	PT52C	1	A20/MPI_BDIP
D21	PT30B	1	A18/MPI_TSIZ0	PT52B	1	A18/MPI_TSIZ0
E21	PT30A	1	MPI_TEA	PT52A	1	MPI_TEA
M20	PT28D	1	D14/MPI_DATA14	PT51D	1	D14/MPI_DATA14
M19	PT28C	1	DP1/MPI_PAR1	PT51C	1	DP1/MPI_PAR1
F21	PT27B	1	A21/MPI_BURST	PT51B	1	A21/MPI_BURST
G21	PT27A	1	D15/MPI_DATA15	PT51A	1	D15/MPI_DATA15
H24	B_REFCLKP_L	-		B_REFCLKP_L	-	
J24	B_REFCLKN_L	-		B_REFCLKN_L	-	
L22	VCC12	-		VCC12	-	
E26	B_VDDIB3_L	-		B_VDDIB3_L	-	
G22	VCC12	-		VCC12	-	
E22	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
F22	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
A21	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
L24	VCC12	-		VCC12	-	
B21	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
D22	B_VDDOB3_L	-		B_VDDOB3_L	-	
B22	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
D23	B_VDDOB2_L	-		B_VDDOB2_L	-	
A22	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
K24	VCC12	-		VCC12	-	
F23	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
E23	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
D26	B_VDDIB2_L	-		B_VDDIB2_L	-	
G23	VCC12	-		VCC12	-	
D27	B_VDDIB1_L	-		B_VDDIB1_L	-	
G24	VCC12	-		VCC12	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

	LFSC/M80			LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AP8	PB117D	4		PB131D	4	
AY3	PB119A	4		PB133A	4	
AW3	PB119B	4		PB133B	4	
AR6	PB119C	4		PB133C	4	
AR5	PB119D	4		PB133D	4	
AU5	PB120A	4		PB134A	4	
AV5	PB120B	4		PB134B	4	
AL12	PB120C	4		PB134C	4	
AL11	PB120D	4		PB134D	4	
AV3	PB121A	4		PB135A	4	
AV4	PB121B	4		PB135B	4	
AN9	PB121C	4		PB135C	4	
AN8	PB121D	4		PB135D	4	
AW1	PB123A	4		PB138A	4	
AY1	PB123B	4		PB138B	4	
AK14	PB123C	4	VREF1_4	PB138C	4	VREF1_4
AK13	PB123D	4		PB138D	4	
AV2	PB124A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D	PB139A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AW2	PB124B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB139B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AM10	PB124C	4		PB139C	4	
AM9	PB124D	4		PB139D	4	
AV1	PB125A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B	PB141A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AU1	PB125B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B	PB141B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AL10	PB125C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C	PB141C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AL9	PB125D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C	PB141D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AT3	PROBE_VCC	-		PROBE_VCC	-	
AU2	PROBE_GND	-		PROBE_GND	-	
AP7	PR95D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A	PR117D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AN7	PR95C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A	PR117C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A
AR3	PR95B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E	PR117B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AR4	PR95A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E	PR117A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AP6	PR94D	3		PR116D	3	
AN6	PR94C	3		PR116C	3	
AT2	PR94B	3		PR116B	3	
AR2	PR94A	3		PR116A	3	
AM6	PR93D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F	PR115D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AL6	PR93C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F	PR115C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AP5	PR93B	3		PR115B	3	
AN5	PR93A	3		PR115A	3	
AL8	PR91D	3		PR112D	3	
AK8	PR91C	3		PR112C	3	
AP2	PR91B	3		PR112B	3	
AN2	PR91A	3		PR112A	3	
AJ12	PR90D	3		PR109D	3	
AH12	PR90C	3		PR109C	3	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-7FFN1020C[1]	-7	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-6FFN1020C[1]	-6	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-5FFN1020C[1]	-5	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-7FFAN1020C	-7	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-6FFAN1020C	-6	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-5FFAN1020C	-5	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-7FCN1152C[2]	-7	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-6FCN1152C[2]	-6	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-5FCN1152C[2]	-5	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-7FFN1152C	-7	Lead-Free Organic fcBGA	1152	COM	40.4
LFSC3GA40E-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	40.4
LFSC3GA40E-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-7FFN1020C[1]	-7	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-6FFN1020C[1]	-6	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-5FFN1020C[1]	-5	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-7FFAN1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-6FFAN1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-5FFAN1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-7FCN1152C[2]	-7	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FCN1152C[2]	-6	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FCN1152C[2]	-5	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-7FFN1152C	-7	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FFN1152C	-6	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FFN1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FCN1152C[1]	-6	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FCN1152C[1]	-5	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FCN1704C[1]	-6	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FCN1704C[1]	-5	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FFN1704C	-6	Lead-Free Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FFN1704C	-5	Lead-Free Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Date	Version	Section	Change Summary
August 2006 (cont.)	01.3 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Family Timing Adders with ispLEVER 6.0 SP1 results
			Updated PLL Timing Parameters based on PDE testing results
			Removed RDDATA parameter from sysCONFIG readback timing table
		Multiple	Changed TDO/RDDATA to TDO
		Pinout Information	Removed all MPI signals from SC15 256 pin package Dual Function Column
			Added note to SC15, SC25 900 pin package that the package supports a 16 bit MPI
			Added note that pin D3 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note that pin D28 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note to SC25 1020 pin package that the package supports a 16 bit MPI
			Added note to SC80 1152 pin package that the package supports a 32 bit MPI
			Added note to SC80 1704 pin package that the package supports a 32 bit MPI
		Ordering Information	Changed “fcBGA” for the 1020 packages to “ffBGA”
November 2006	01.4	Introduction	LatticeSC Family Selection Guide table – I/O count for SC80 device, 1704 fcBGA package changed to 904/32. I/O count for SC115 device, 1704 fcBGA package changed to 942/32.
		DC and Switching Characteristics	DC Electrical Characteristics table – Updated the initialization and standby supply current values.
			DC Electrical Characteristics table – Updated the sysCONFIG Master Parallel mode RCLK low and RCLK high time specifications.
			DC Electrical Characteristics table – Updated VCCIO values for LVPECL33 I/Os.
		Pin Information	Pin Information Summary table - Changed number of single ended user I/Os from 906 to 904 for 1704 fcBGA.
			Removed the single-ended only output restriction on pins D3 and D28 in an SC15 and SC25 900 pin package.
		Ordering Information	Ordering Information tables - Changed number of I/Os from 906 to 904 for 1704 fcBGA.
			Added ordering part numbers for LatticeSC/SCM 40K and 115K LUT devices.
			Added lead-free ordering part numbers.
		Multiple	Changed number of available SC80 I/O from 906 to 904.
			Changed number of available SC115 I/O from 944 to 942.
January 2007	01.4a	Architecture	Added EBR Asynchronous Reset section.
February 2007	01.4b	Architecture	Updated EBR Asynchronous Reset section.
March 2007	01.5	Architecture	Added EBR asynchronous reset clarification
			Clarified that differential drivers are not supported in banks 1, 4 and 5
		DC and Switching Characteristics	Added clarification for the description of the junction temperature specification in the Absolute Maximum Ratings section.
			Updated Initialization and Standby Current table.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.1 SP1 results.